

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-25	V
Gate-Source Voltage			V _{GSS}	-8	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-0.17 -0.14	А
Continuous Drain Current (Note 6) V_{GS} = -2.7V Steady T_A = +25°C T_A = +70°C		I _D	-0.15 -0.12	А	
Pulsed Drain Current T _P ≤ 300μs, Duty Cycle = 2%)			I _{DM}	-0.5	А

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Dower Dissination	(Note 5)	Б	0.33	· w
Total Power Dissipation	(Note 6)	P _D	0.45	
Thermal Begintance, Junction to Ambient	(Note 5)	В	376	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{ heta JA}$	275	
Thermal Resistance, Junction to Case	(Note 6)	R ₀ JC	81	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

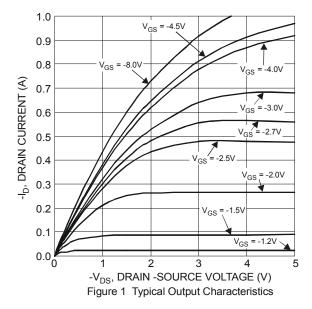
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

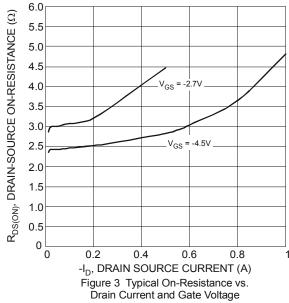
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-25	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1	μA	V _{DS} = -20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	_	_	-100	nA	V_{GS} = -8V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	-0.65	-0.96	-1.5	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	2.5	10	Ω	$V_{GS} = -4.5V, I_D = -0.2A$
Static Dialii-Source Off-Resistance		_	3	13		$V_{GS} = -2.7V, I_D = -0.05A$
Forward Transfer Admittance	Y _{fs}	_	189	_	ms	V _{DS} = -5V, I _D = -0.2A
Diode Forward Voltage (Note 7)	V _{SD}	_	_	-1.5	V	V _{GS} = 0V, I _S = -0.2A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	27.2	_		V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	Coss	_	6.1	_	pF	
Reverse Transfer Capacitance	C _{rss}	_	1.7	_		
Total Gate Charge	Qg	_	0.35	_		V _{DS} = -5V, I _D = -0.2A, V _{GS} = -4.5V,
Gate-Source Charge	Q _{gs}	_	0.08	_	nC	
Gate-Drain Charge	Q _{gd}	_	0.06	_		
Turn-On Delay Time	t _{d(on)}	_	4.5	_		$V_{GS} = -4.5V, V_{DD} = -6V$ $I_{D} = -0.2A, R_{G} = 50\Omega$
Rise Time	t _r	_	2.3	_		
Turn-Off Delay Time	t _{d(off)}	_	24.1	_	ns	
Fall Time	t _f	_	11.0	_		

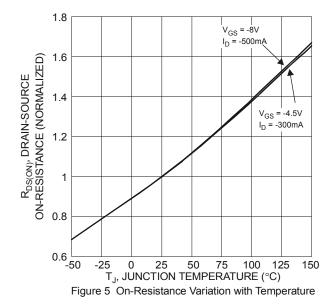
Notes:

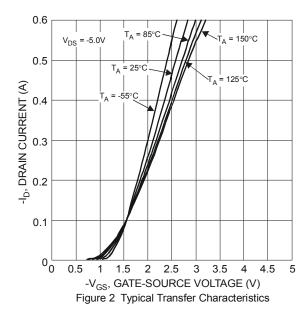
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.

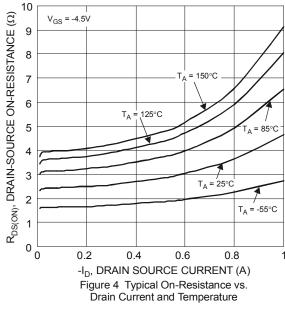












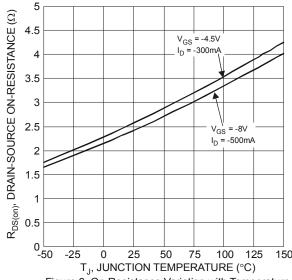


Figure 6 On-Resistance Variation with Temperature



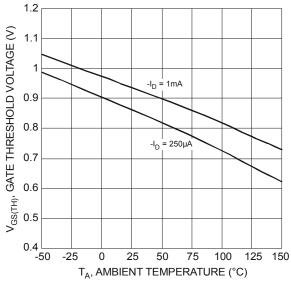
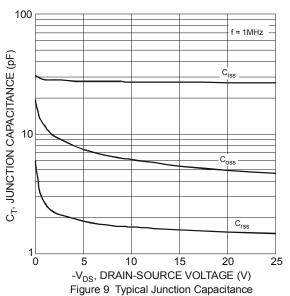
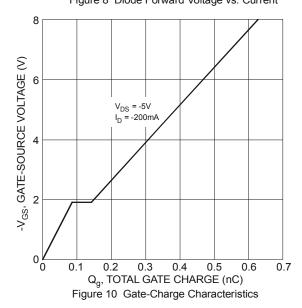
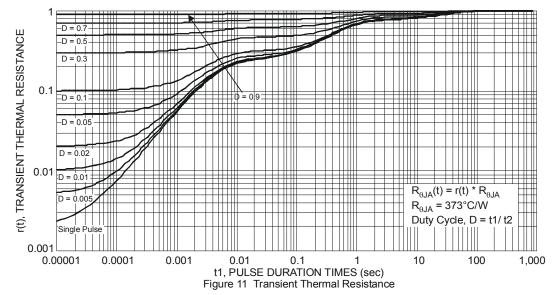


Figure 7 Gate Threshold Variation vs. Ambient Temperature



1 0.8 -I_S, SOURCE CURRENT (A) 0.6 0.4 T_A= 25°C 0.2 0 0 0.3 0.6 0.9 1.2 1.5 $-V_{SD}$, SOURCE-DRAIN VOLTAGE (V) Figure 8 Diode Forward Voltage vs. Current

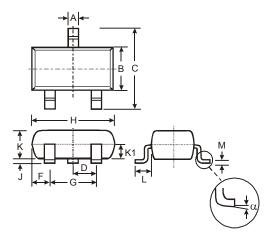






Package Outline Dimensions

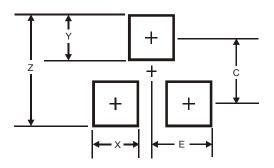
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23						
Dim	Min	Max	Тур			
Α	0.37	0.51	0.40			
В	1.20	1.40	1.30			
С	2.30	2.50	2.40			
D	0.89	1.03	0.915			
F	0.45	0.60	0.535			
G	1.78	2.05	1.83			
Н	2.80	3.00	2.90			
J	0.013	0.10	0.05			
K	0.903	1.10	1.00			
K1	-	-	0.400			
L	0.45	0.61	0.55			
M	0.085	0.18	0.11			
α	0°	8°	-			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.9
Х	8.0
Y	0.9
С	2.0
E	1.35



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